

METHOD FOR MANUFACTURING ELECTRONIC DEVICE

ABSTRACT

A method for manufacturing an electronic device (10) is provided. The method includes providing a substrate (12) having a plurality of radio-frequency components (14) provided thereon, the radio-frequency components (14) including an antenna (16) and a matching circuitry (18). A cap (20) is attached to the substrate (12) over the antenna (16) and the matching circuitry (18) and a molding operation is performed to encapsulate the cap (20) and at least a portion of the substrate (12) with a mold compound (28).

10 [FIG. 1D]